

QUAD FORWARD-CONDUCTING P-GATE THYRISTORS PROGRAMMABLE OVERVOLTAGE PROTECTORS

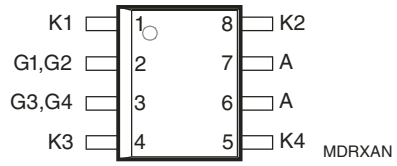
TISP6NTP2C High Voltage Ringing SLIC Protector

Independent Tracking Overvoltage Protection for Two SLICs:
- **Dual Voltage-Programmable Protectors**
- **Supports Battery Voltages Down to -155 V**
- **Low 5 mA max. Gate Triggering Current**
- **High 150 mA min. (70 °C) Holding Current**
- **Specified 2/10 Limiting Voltage**
- **Small Outline Surface Mount Package**
- **Full 0 °C to 70 °C Temperature Range**

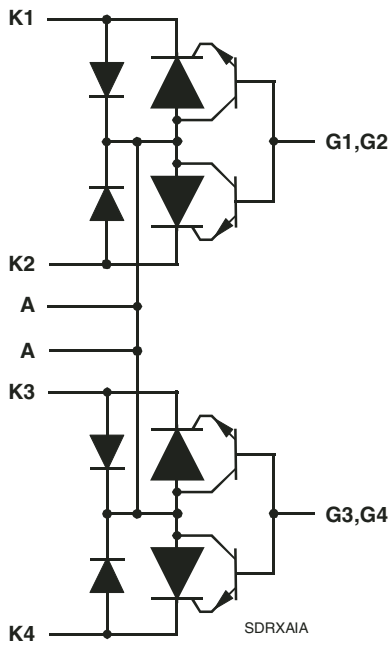
Rated for Common Impulse Waveforms

Voltage Impulse Wave Shape	Current Impulse Wave Shape	I_{PPSM} A
10/1000	10/1000	25
10/700	5/310	40
2/10	2/10	90

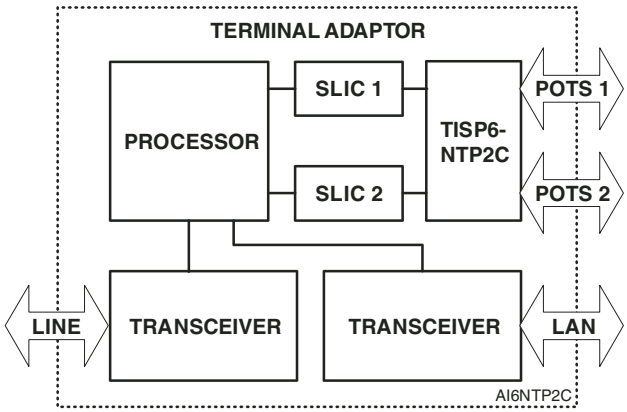
D Package (Top View)



Device Symbol



Typical TISP6NTP2C Router Application



..... **UL Recognized Components**

Description

The TISP6NTP2C has been designed for short loop systems such as:
– WILL (Wireless In the Local Loop)
– FITL (Fibre In The Loop)
– DAML (Digital Added Main Line, Pair Gain)
– SOHO (Small Office Home Office)
– ISDN-TA (Integrated Services Digital Network - Terminal Adaptors)

How to Order

Device	Package	Carrier	For Standard Termination Finish Order As	For Lead Free Termination Finish Order As
TISP6NTP2C	D (8-pin Small-Outline)	R (Embossed Tape Reeled)	TISP6NTP2CDR	TISP6NTP2CDR-S
		- (Tube)	TISP6NTP2CD	TISP6NTP2CD-S

*RoHS Directive 2002/95/EC Jan 27 2003 including Annex
MARCH 2002 – REVISED FEBRUARY 2005
Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.

Description (Continued)

The systems described often have the need to source two POTS (Plain Old Telephone Service) lines, one for a telephone and the other for a facsimile machine. In a single surface mount package, the TISP6NTP2C protects the two POTS line SLICs (Subscriber Line Interface Circuits) against overvoltages caused by lightning, a.c. power contact and induction.

The TISP6NTP2C has an array of four buffered P-gate forward conducting thyristors with twin commoned gates and a common anode connection. Each thyristor cathode has a separate terminal connection. An antiparallel anode-cathode diode is connected across each thyristor. The buffer transistors reduce the gate supply current.

In use, the cathodes of an TISP6NTP2C thyristors are connected to the four conductors of two POTS lines (see applications information). Each gate is connected to the appropriate negative voltage battery feed of the SLIC driving that line pair. By having separate gates, each SLIC can be protected at a voltage level related to the negative supply voltage of that individual SLIC. The anode of the TISP6NTP2C is connected to the SLIC common. The TISP6NTP2C voltage and current ratings also make it suitable for the protection of ISDN d.c. feeds of down to -115 V (ETSI Technical Report ETR 080:1993, ranges 1 to 5).

Positive overvoltages are clipped to common by forward conduction of the TISP6NTP2C antiparallel diode. Negative overvoltages are initially clipped close to the SLIC negative supply by emitter follower action of the TISP6NTP2C buffer transistor. If sufficient clipping current flows, the TISP6NTP2C thyristor will regenerate and switch into a low voltage on-state condition. As the overvoltage subsides, the high holding current of the TISP6NTP2C prevents d.c. latchup.

Absolute Maximum Ratings, 0 °C ≤ T_J ≤ 70 °C (Unless Otherwise Noted)

Rating	Symbol	Value	Unit
Repetitive peak off-state voltage, V_{GK} = 0	V_{DRM}	-170	V
Repetitive peak gate-cathode voltage, V_{KA} = 0	V_{GKRM}	-167	V
Non-repetitive peak on-state pulse current (see Notes 1 and 2)	I_{PPSM}		A
10/1000 (Telcordia (Bellcore) GR-1089-CORE, Issue 2, February 1999, Section 4)		25	
5/320 (ITU-T K.20, K.21& K.45, K.44 open-circuit voltage wave shape 10/700)		40	
2/10 (Telcordia (Bellcore) GR-1089-CORE, Issue 2, February 1999, Section 4)		90	
Non-repetitive peak on-state current, 50 Hz/60 Hz (see Notes 1 and 2)	I_{TSM}		A
0.1 s		7	
1 s		2.7	
5 s		1.5	
300 s		0.45	
900 s		0.43	
Non-repetitive peak gate current, 1/2 µs pulse, cathodes commoned (see Note 1)	I_{GSM}	+25	A
Operating free-air temperature range	T_A	-40 to +85	°C
Junction temperature	T_J	-40 to +150	°C
Storage temperature range	T_{stg}	-40 to +150	°C

NOTES: 1. Initially, the protector must be in thermal equilibrium. The surge may be repeated after the device returns to its initial conditions. Gate voltage range is -20 V to -155 V.

2. These non-repetitive rated currents are peak values for either polarity. The rated current values may be applied to any cathode-anode terminal pair. Additionally, all cathode-anode terminal pairs may have their rated current values applied simultaneously (in this case the anode terminal current will be four times the rated current value of an individual terminal pair).

Recommended Operating Conditions

Component		Min	Typ	Max	Unit
C_G	Gate decoupling capacitor	100	220		nF
R_S	Series resistor for GR-1089-CORE intra-building surge survival, section 4.5.9, tests 1 and 2	5	50		Ω
	Series resistor for K.20, K.21 and K.45 coordination with a 400 V primary protector	10	50		Ω

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Electrical Characteristics, 0 °C ≤ T_J ≤ 70 °C (Unless Otherwise Noted)

Parameter		Test Conditions		Min	Typ	Max	Unit
I_D	Off-state current	$V_D = V_{DRM}$, $V_{GK} = 0$	T_J = 25 °C			-5	μA
						-50	μA
$V_{(BO)}$	Ramp breakover voltage	UL 497B, dv/dt ≤±100 V/μs, di/dt = ±10 A/μs, V_{GG} = -100 V, Maximum ramp value = ±10 A	T_J = 25 °C			-112	V
$V_{(BO)}$	Impulse breakover voltage	2/10 μs, I_{TM} = -27 A, di/dt = -27 A/μs, R_S = 50 Ω, V_{GG} = -100 V, (see Note 3)				-115	V
$V_{GK(BO)}$	Gate-cathode impulse breakover voltage	2/10 μs, I_{TM} = -27 A, di/dt = -27 A/μs, R_S = 50 Ω, V_{GG} = -100 V, (see Note 3)				15	V
V_F	Forward voltage	I_F = 5 A, t_w = 200 μs				3	V
V_{FRM}	Ramp peak forward recovery voltage	UL 497B, dv/dt ≤±100 V/μs, di/dt = ±10 A/μs, Maximum ramp value = ±10 A	T_J = 25 °C			5	V
V_{FRM}	Impulse peak forward recovery voltage	2/10 μs, I_{TM} = -27 A, di/dt = -27 A/μs, R_S = 50 Ω, (see Note 3)				12	V
I_H	Holding current	I_T = -1 A, di/dt = 1A/ms, V_{GG} = -100 V		-150			mA
I_{GKS}	Gate reverse current	$V_{GG} = V_{GK} = V_{GKRM}$, $V_{KA} = 0$	T_J = 25 °C			-5	μA
						-50	μA
I_{GT}	Gate trigger current	I_T = -3 A, $t_{p(g)}$ ≥ 20 μs, V_{GG} = -100 V	T_J = 25 °C			5	mA
						6	mA
V_{GT}	Gate-cathode trigger voltage	I_T = -3 A, $t_{p(g)}$ ≥ 20 μs, V_{GG} = -100 V				2.5	V
C_{KA}	Cathode-anode off-state capacitance	f = 1 MHz, V_d = 1 V, I_G = 0, (see Note 4)	V_D = -3 V			100	pF
			V_D = -48 V			50	pF

NOTES: 3. GR-1089-CORE intra-building 2/10, 1.5 kV conditions with 20 MHz bandwidth. The diode forward recovery and the thyristor gate impulse breakover (overshoot) are not strongly dependent of the SLIC supply voltage value (V_{GG}).

4. These capacitance measurements employ a three terminal capacitance bridge incorporating a guard circuit. The unmeasured device terminals are a.c. connected to the guard terminal of the bridge.

Thermal Characteristics

Parameter		Test Conditions	Min	Typ	Max	Unit
$R_{\theta JA}$	Junction to free air thermal resistance	T_A = 70 °C, EIA/JESD51-3 PCB, EIA/JESD51-2 environment, P_{tot} = 0.52 W			160	°C/W

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Parameter Measurement Information

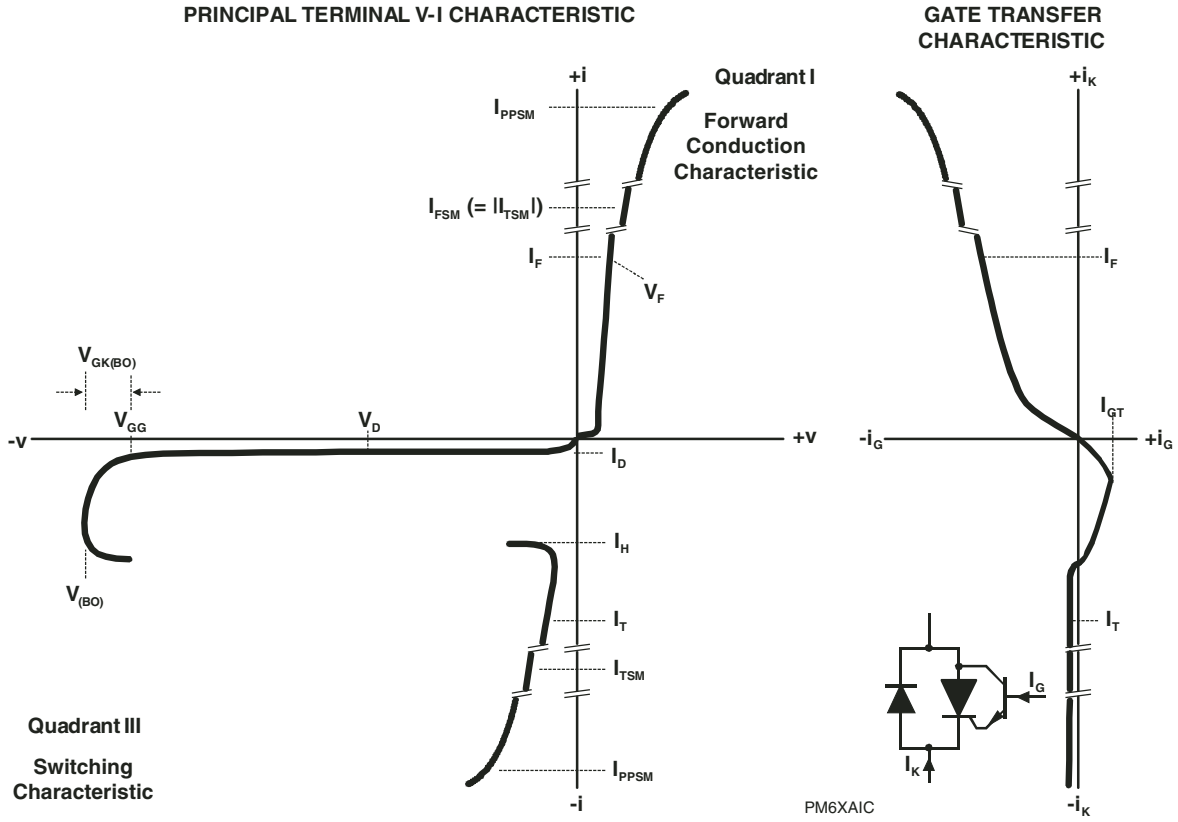


Figure 1. Principal Terminal and Gate Transfer Characteristics

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APPLICATIONS INFORMATION

SLIC Protection

The generation of POTS lines at the customer premise normally uses a ringing SLIC. Although the lines are short, a central office ringing voltage level is often required for fax machine operation. High voltage SLICs are now available that can produce adequate ringing voltage (see table). The TISP6NTP2C has been designed to work with these SLICs which use battery voltages, V_{BATH}, down to -150 V. Figure 2 shows a typical example with one TISP6NTP2C protecting two SLICs.

The table below shows some details of HV SLICs using multiple negative supply rails.

Manufacturer	INFINEON‡	LEGERITY™‡			Unit
SLIC Series	SLIC-P‡	ISLIC™‡			
SLIC #	PEB 4266	79R241	79R101	79R100	
Data Sheet Issue	14/02/2001	-/08/2000	-/07/2000	-/07/2000	
Short Circuit Current	110	150	150	150	mA
V_{BATH} max.	-155	-104	-104	-104	V
V_{BATL} max.	-150	-104	V_{BATH}	V_{BATH}	V
AC Ringing for:	85	45†	50†	55†	V rms
Crest Factor	1.4	1.4	1.4	1.25	
V_{BATH}	-70	-90	-99	-99	V
V_{BATR}	-150	-36	-24	-24	V
R or T Overshoot < 250 ns		-15 15	-20 12	-20 12	V
Line Feed Resistance	20 + 30	50	50	50	Ω

† Assumes -20 V battery voltage during ringing.
‡ Legerity, the Legerity logo and ISLIC are the trademarks of Legerity, Inc.
Other product names used in this publication are for identification purposes only and may be trademarks of their respective companies.

ISDN Protection

For voltage feed protection, the cathodes of an TISP6NTP2C thyristors are connected to the four conductors to be protected (see Figure 3). Each gate is connected to the appropriate negative voltage feed. The anode of the TISP6NTP2C is connected to the system common. Positive overvoltages are clipped to common by forward conduction of the TISP6NTP2C antiparallel diode. Negative overvoltages are initially clipped close to the negative supply by emitter follower action of the TISP6NTP2C buffer transistor. If sufficient clipping current flows, the TISP6NTP2C thyristor will regenerate and switch into a low voltage on-state condition. As the negative overvoltage subsides, the high holding current of the TISP6NTP2C prevents d.c. latchup.

Voltage Stress Levels

Figure 4 shows the protector electrodes. The package terminal designated gate, G, is the transistor base, B, electrode connection and so is marked as B (G). The following junctions are subject to voltage stress: Transistor EB and CB, SCR AK (off state) and the antiparallel diode (reverse blocking). This clause covers the necessary testing to ensure the junctions are good.

Testing transistor CB and EB: The maximum voltage stress level for the TISP6NTP2C is V_{BATH} with the addition of the short term antiparallel diode voltage overshoot, V_{FRM}. The current flowing out of the G terminal is measured at V_{BATH} plus V_{FRM}. The SCR K terminal is shorted to the common (0 V) for this test (see Figure 4). The measured current, I_{GKS}, is the sum of the junction currents I_{CB} and I_{EB}.

Testing transistor CB, SCR AK off state and diode reverse blocking: The highest AK voltage occurs during the overshoot period of the protector. To make sure that the SCR and diode blocking junctions do not break down during this period, a d.c. test for off-state current, I_D, can be applied at the overshoot voltage value. To avoid transistor CB current amplification by the transistor gain, the transistor base-emitter is shorted during this test (see Figure 5).

Summary: Two tests are need to verify the protector junctions. Maximum current values for I_{GKS} and I_D are required at the specified applied voltage conditions.

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APPLICATIONS INFORMATION

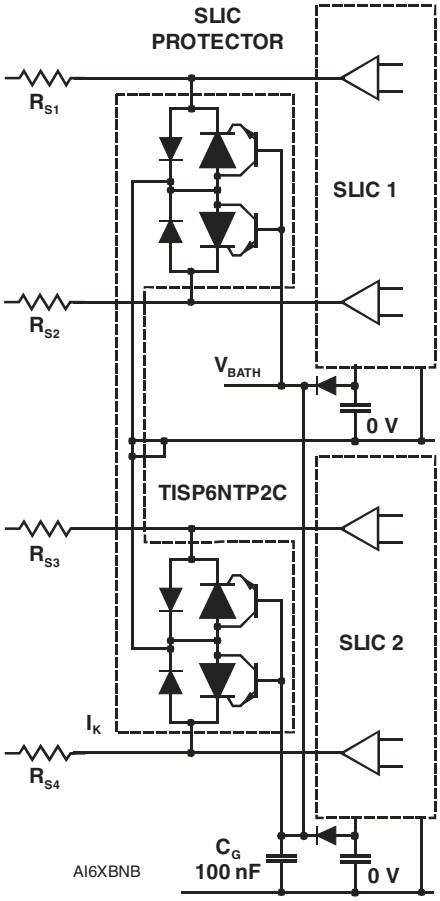
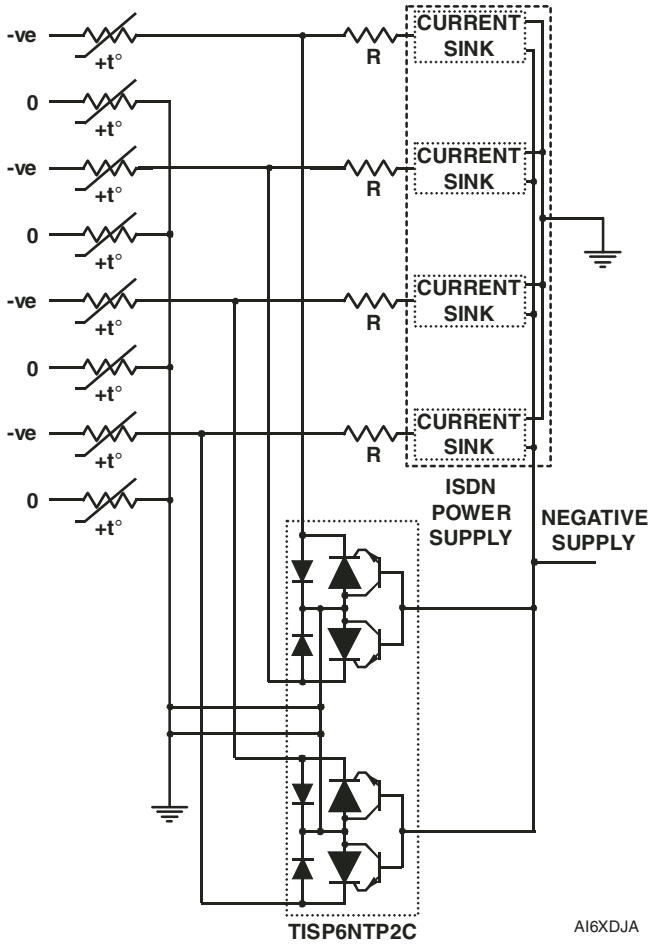


Figure 2. SLIC Protection



Resistor "R" may be needed if sink has internal clamp diode

Figure 3. Protection of Four ISDN Power Feeds

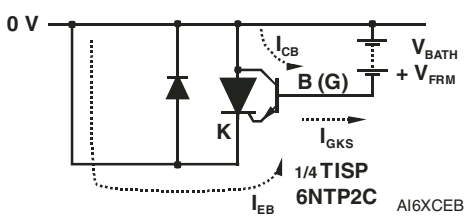
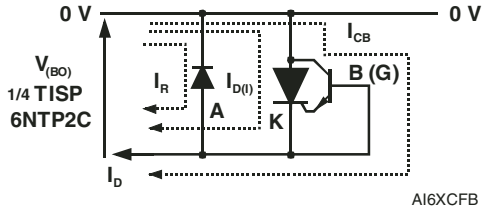


Figure 4. Transistor CB and EB Verification



$I_{D(I)}$ is the internal SCR value of I_D

Figure 5. Off-State Current Verification

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MECHANICAL DATA

Device Symbolization Code

Devices will be coded as below.

Device	Symbolization Code
TISP6NTP2C	6NTP2C

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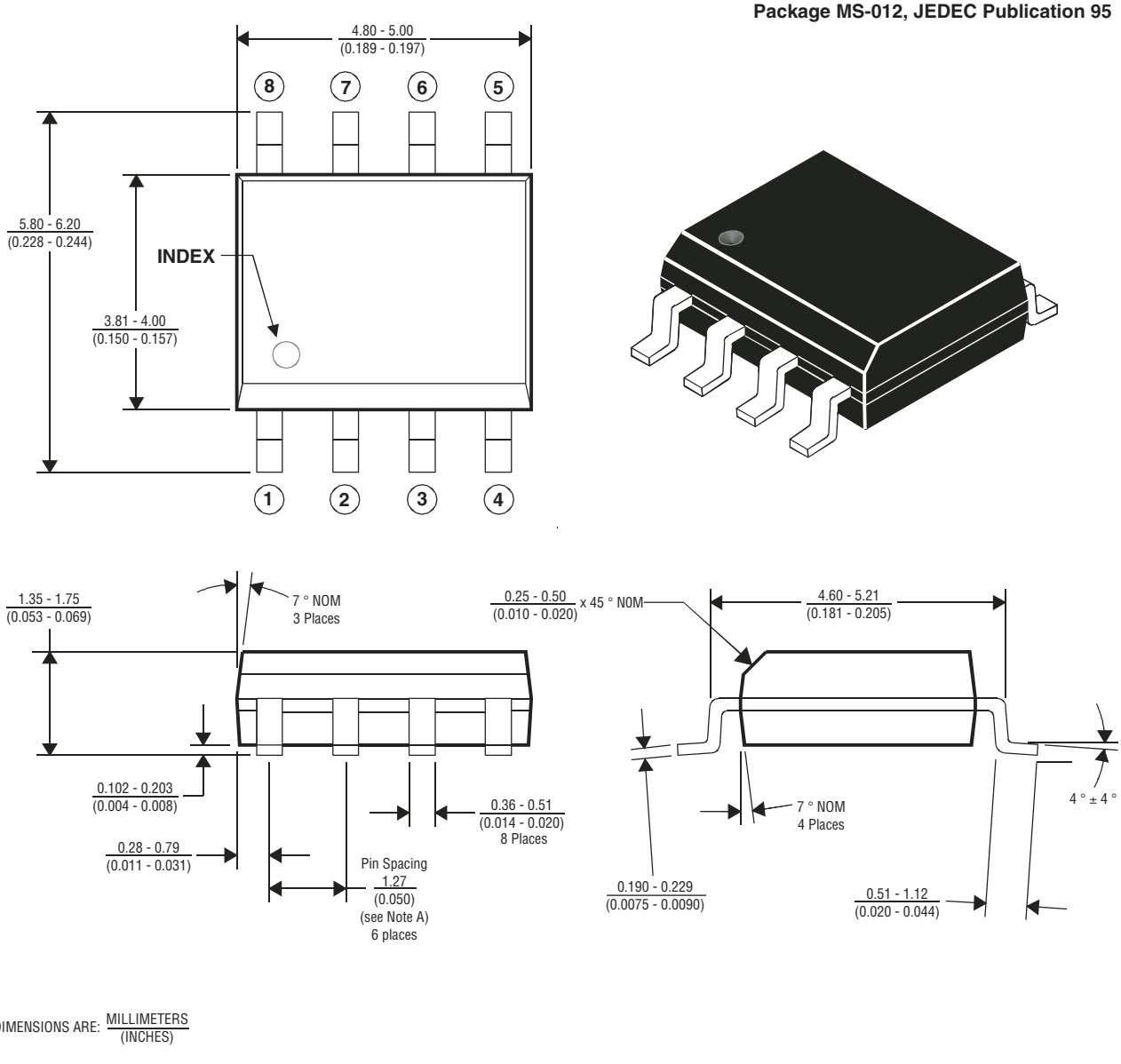
MECHANICAL DATA

D008 Plastic Small-Outline Package

This small-outline package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.

D008

8-pin Small Outline Microelectronic Standard Package MS-012, JEDEC Publication 95



MDXXAAF

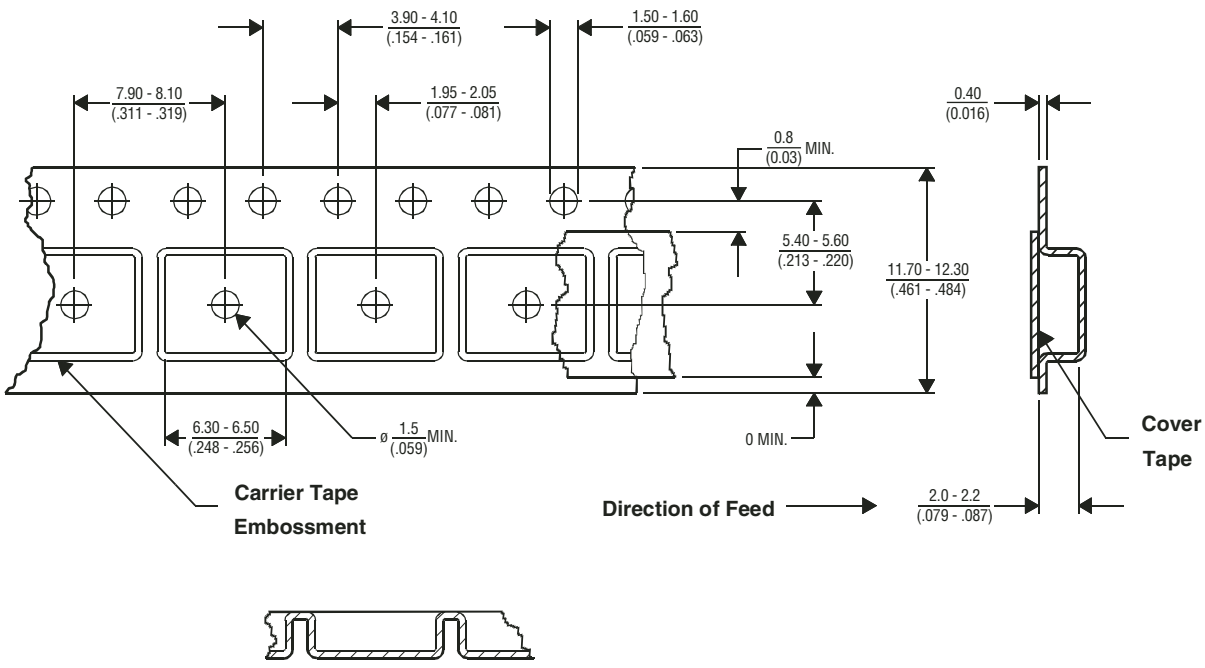
NOTES: A. Leads are within 0.25 (0.010) radius of true position at maximum material condition.
B. Body dimensions do not include mold flash or protrusion.
C. Mold flash or protrusion shall not exceed 0.15 (0.006).
D. Lead tips to be planar within ±0.051 (0.002).

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MECHANICAL DATA

D008 - Tape Dimensions

D008 Package (8-pin Small Outline) Single-Sprocket Tape



DIMENSIONS ARE: MILLIMETERS / (INCHES)

NOTES: A. Taped devices are supplied on a reel of the following dimensions:-

MDXXATD

Reel diameter:	330 +0.0/-4.0 (12.99 +0.0/-.157)
Reel hub diameter:	100 ± 2.0 (3.937 ± .079)
Reel axial hole:	13.0 ± 0.2 (.512 ± .008)

B. 2500 devices are on a reel.

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